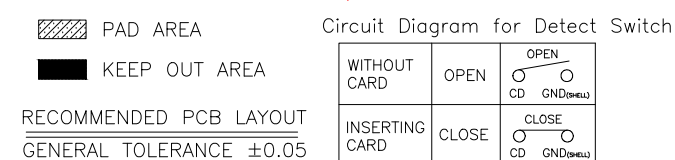
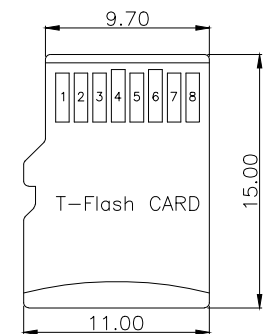
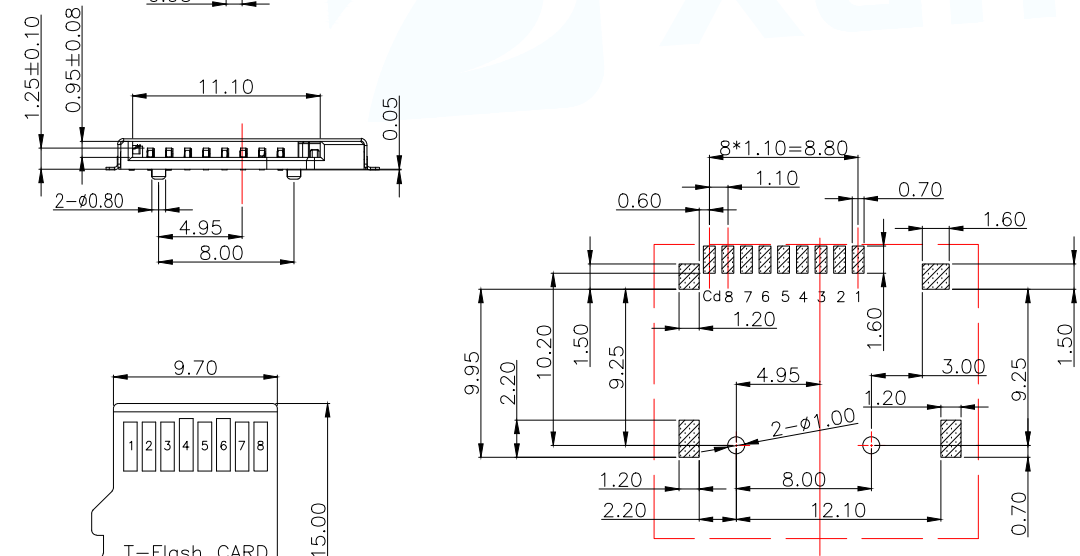
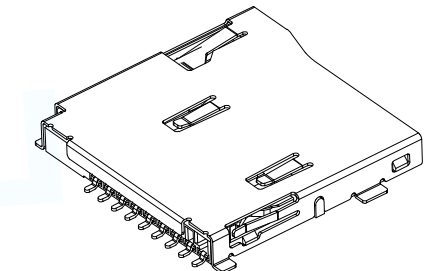


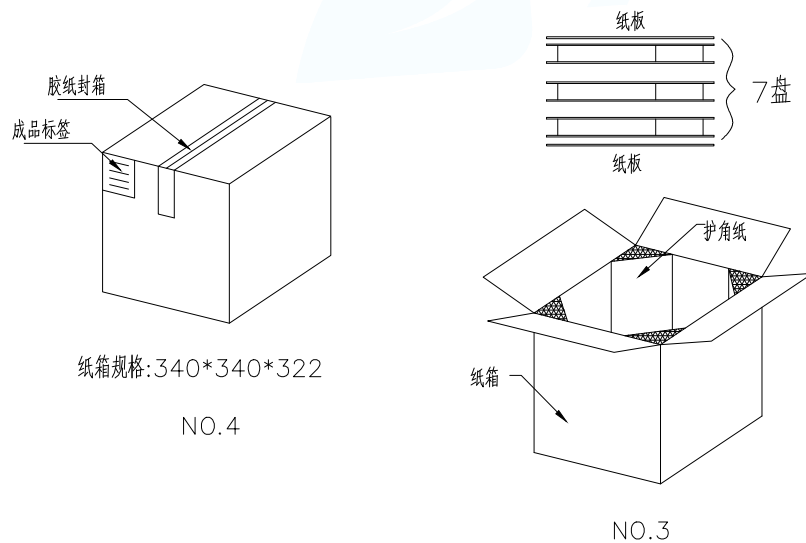
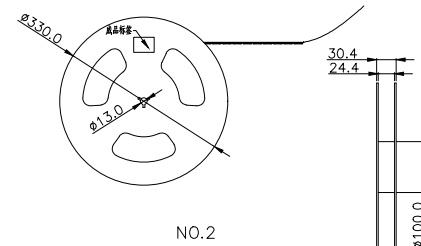
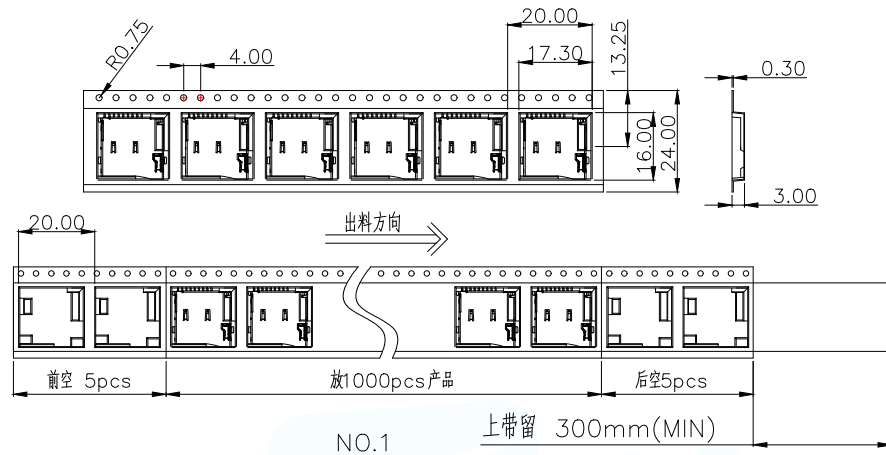
Specification:

- Electrical Characteristics:
  - Contact Current Rating:0.5 Amperes.
  - Dielectric Withstanding Voltage:AC500V r.m.s.
  - Insulation Resistance:1000 MΩ Minimum.
  - Contact Resistance:40 mΩ Maximum.
- Environmental:
  - Operating Temperature:-25°C~+90°C.
- Environmental:
  - Mating Cycles:5,000 Insertions.
- Mechanical Characteristics:
  - Card Push Insertion/Out Force:0.2~1.40kgf.
  - Contact Separation Force:0.20kgf Minimum.
- Material:
  - Insulator:HI-Temp Plastic UL 94V-0 Rated.
  - Contact:Copper Alloy(t=0.15mm).
  - Shell:Stainless Steel(t=0.15mm).
  - Spring:SWP.



TF CARD PIN DEFINE			
PIN NO.	NAME	YYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MICRO SD CARD PUSH PUSH SMT 端子镀半金零锡 双弹片
DECIMALS:	ANGLES:		PAR TF-115YY-BCP9
X.X:±0.35	X.X':±3°		DWN
X.XX:±0.25	X.XX':±2°		CHKD
X.XXX:±0.15		APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1
			REV:A



1. 材质要求:

- 1.1 纸箱的材质为K=K;外形尺寸为34\*34\*32.2;
- 1.2 卷盘的材质为PS,卷盘的外形尺寸为 $\phi 330*30.4$ ;

2. 包装方式:

- 2.1 将卷带放入包装机后,前空5PCS,后放产品1000PCS,再后空5PCS;上带留300MM长度。
- 2.2 将包装好的产品从包装机上取下并包装好,贴上内盘标签;
- 2.3 把累叠好的7盘叠放入纸箱中共计7Kset,上下放纸板;
- 2.4 把包装好的成品打包封箱,并在纸箱外贴上标签

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
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X.XXX:±0.15		APVD	SCALE 1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1
			REV:A

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